

LAMINATE AND METHOD FOR PRODUCING SAME

ABSTRACT

The object of the present invention is to provide a metallic material which is applicable to a constituent member
5 of a semiconductor production device and has excellent corrosion resistance, particularly corrosion resistance to acids and high-temperature steam. A laminate according to the present invention comprises a metallic base material, a nickel-containing plating film layer formed on the metallic base
10 material, and a gold plating film layer formed on the nickel-containing plating film layer, in which pinholes in the gold plating film layer are sealed with a passive film having a thickness of 15 nm or greater.

[Fig. 1]